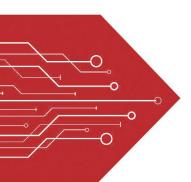
MSKSEMI















ESD

TVS

TSS

MOV

GDT

PLED

Broduct data sheet







SOT-323

- 1. BASE
- 2. EMITTER
- 3. COLLECTOR

S9014W

TRANSISTOR (NPN)

FEATURES

- Complementary to S9015W
- Small Surface Mount Package

MAXIMUM RATINGS (T_a=25℃ unless otherwise noted)

Symbol	Parameter	Value	Unit
V _{CBO}	Collector-Base Voltage	50	V
V _{CEO}	Collector-Emitter Voltage	45	V
V _{EBO}	Emitter-Base Voltage	5	V
Ic	Collector Current	100	mA
Pc	Collector Power Dissipation	200	mW
R _{OJA}	Thermal Resistance From Junction To Ambient	625	°C/W
T _J ,T _{stg}	Operation Junction and Storage Temperature Range	-55~+150	℃

ELECTRICAL CHARACTERISTICS (T_a=25°C unless otherwise specified)

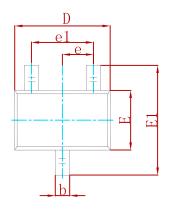
Parameter	Symbol	Test conditions	Min	Тур	Max	Unit
Collector-base breakdown voltage	$V_{(BR)CBO}$	I _C =100μA, I _E =0	50			V
Collector-emitter breakdown voltage	$V_{(BR)CEO}$	I _C =100μA, I _B =0	45			V
Emitter-base breakdown voltage	$V_{(BR)EBO}$	I _E =100μA, I _C =0	5			V
Collector cut-off current	I _{CBO}	V _{CB} =50V, I _E =0			100	nA
Collector cut-off current	I _{CEO}	V _{CE} =35V, I _B =0			1	uA
Emitter cut-off current	I _{EBO}	V _{EB} =4V, I _C =0			100	nA
DC current gain	h _{FE}	V _{CE} =5V, I _C =1mA	200		1000	
Collector-emitter saturation voltage	$V_{CE(sat)}$	I _C =100mA, I _B =5mA			0.3	V
Base-emitter saturation voltage	$V_{BE(sat)}$	I _C =100mA, I _B =5mA			1	V
Base-emitter voltage	V_{BE}	V _{CE} =5V, I _C =2mA	0.58		0.7	V
Transition frequency	f⊤	V _{CE} =5V,I _C =10mA, f=30MHz	150			MHz
Collector output capacitance	C _{ob}	V _{CB} =10V, I _E =0, f=1MHz			3.5	pF

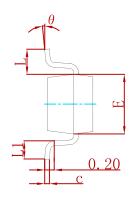
CLASSIFICATION OF h_{FE}

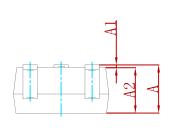
RANK	L	Н
RANGE	200 - 450	450 - 1000
MARKING	J6	



PACKAGE MECHANICAL DATA

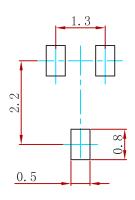






Cumbal	Dimensions In Millimeters		Dimensions In Inches		
Symbol	Min	Max	Min	Max	
Α	0.900	1.100	0.035	0.043	
A1	0.000	0.100	0.000	0.004	
A2	0.900	1.000	0.035	0.039	
b	0.200	0.400	0.008	0.016	
С	0.080	0.150	0.003	0.006	
D	2.000	2.200	0.079	0.087	
E	1.150	1.350	0.045	0.053	
E1	2.150	2.450	0.085	0.096	
е	0.650) TYP	0.026	6 TYP	
e1	1.200	1.400	0.047	0.055	
L	0.525	REF	0.02	I REF	
L1	0.260	0.460	0.010	0.018	
θ	0°	8°	0°	8°	

Suggested Pad Layout



Note:

- 1. Controlling dimension:in millimeters.
- 2.General tolerance:±0.05mm.
- 3. The pad layout is for reference purposes only.

REEL SPECIFICATION

P/N	PKG	QTY
S9014W	SOT-323	3000



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